

SPECIFICATION OF LED CHIP

C1650-30

[NIR]

1) Commodity Type and Physical Characteristics.

- | | | | |
|----------------------|------------------|------------------|------------|
| 1. Material | InGaAsP/InP(DDH) | | |
| 2. Electrode | Top Side | P (anode) side | : Au Alloy |
| | Bottom Side | N (cathode) side | : Au Alloy |
| 3. Electrode Pattern | Fig.1 | | |
| 4. Chip Size | Fig.2 | | |
| 5. Chip Thickness | Fig.2 | | |
| 6. Emission Area | Fig.2 | | |

2) Electro-Optical Characteristics

parameters	symbol	condition	min.	typ.	max.	unit
Forward Voltage	Vf	If=20mA		0.78	1.2	V
		If=50mA		0.85	1.3	
Reverse Current	Ir	Vr=3V			10	uA
Power Intensity	Po	If=20mA		0.75		mW
		If=50mA		1.50		
Wavelength	peac	λ_P	1600	1650	1700	nm
	centroid	λ_C		1615		
Spectral Radiation Bandwidth	$\Delta\lambda$	If=50mA		130		nm
RiseTime	t r	If=20mA		40		ns
FallTime	t f	If=20mA		40		ns

‡ Die shall be mounted on TO=18 gold header without resin coated. (Ta=25°C)

[Unit: um]

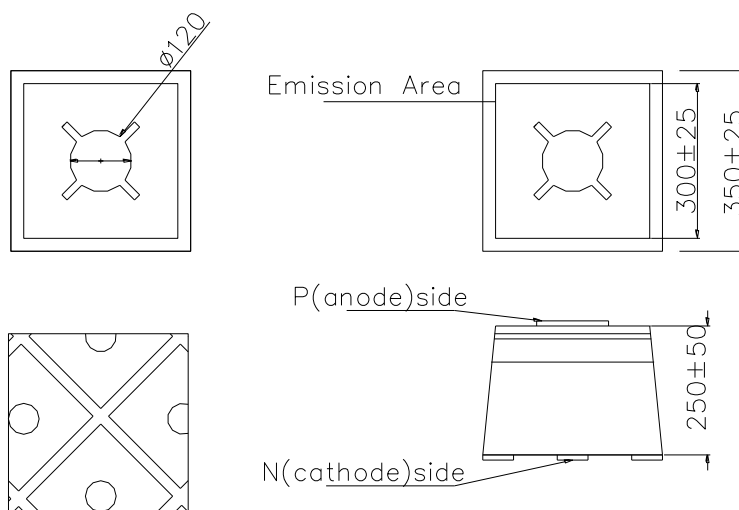


Fig.1 Electrode Pattern

Fig.2 Chip size and Emission Area